

Title (en)
COMPOSITION FOR PRODUCING A CONDUCTIVE COMPOSITE MATERIAL CONTAINING A POLYANILINE, AND RESULTING COMPOSITE MATERIAL

Title (de)
ZUSAMMENSETZUNG ZUR HERSTELLUNG EINES LEITFÄHIGEN VERBUNDMATERIAL MIT EINEM POLYANILIN UND MIT DIESER ZUSAMMENSETZUNG HERGESTELLTES MATERIAL

Title (fr)
COMPOSITION POUR LA FABRICATION D'UN MATERIAU COMPOSITE CONDUCTEUR CONTENANT UNE POLYANILINE ET MATERIAU COMPOSITE OBTENU A PARTIR DE CETTE COMPOSITION

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Application
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Abstract (en)
[origin: WO9805040A1] Compositions for producing composite materials containing a polyaniline are disclosed. The compositions consist of a solution of the following components in a solvent such as m-cresol: (a) a conductive polyaniline protonated by a protonating agent capable of promoting polyaniline dissolution in the solvent, e.g. phenylphosphonic acid; (b) an insulating polymer selected, e.g., from cellulose polymers and polyvinyl chlorides, e.g. cellulose acetate; and (c) an insulating plasticiser such as a mixture of dimethyl phthalate, diethyl phthalate and triphenyl phosphate. The solution may be cast and the solvent evaporated off to give a flexible film of conductive composite material having good electrical and mechanical properties.

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